



# Release Notes

## WinCE BSP for the TI OMAP35x EVM

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**TABLE 1. REVISION HISTORY**

<b>Revision</b>	<b>Date</b>	<b>By</b>	<b>Description</b>
1.0	Sep 15, 2009	Kevin Hasley	Initial release
1.1	Sep 17, 2009	Kevin Hasley	Update with EVM details
1.2	Oct 14, 2009	Kevin Hasley	Added EVM2 details
1.3	Oct 15, 2009	Kevin Hasley	Added information about EVM2 batch file
1.4	Oct 21, 2009	Kevin Hasley	Updated release notes in build section
1.5	Oct 22, 2009	Kevin Hasley	Change in BSP information
1.6	Dec 14, 2009	Kevin Hasley	Preparing for 6.01.04 release

## Contents

1.	Introduction .....	5
2.	Release Description.....	5
2.1.	Release Highlights .....	5
2.2.	Release Notices .....	6
2.2.1.	Nomenclature .....	6
2.2.2.	Sample Build Scripts.....	6
2.2.3.	Sample OS Design .....	6
2.2.4.	Prebuilt Images .....	7
2.2.5.	Sample Drivers .....	7
2.2.6.	New Directory Structure .....	7
3.	Installation .....	8
4.	Build Instructions .....	9
4.1.	Downloading WinCE Image Using Platform Builder .....	9
4.2.	Programming Bootloader Into NAND/ONENAND.....	10
4.3.	Booting from NAND .....	10
4.4.	Booting from SD Memory Card (SD Boot).....	11
5.	Test Results .....	12
6.	Known Issues.....	13
6.1.	BSP .....	13
6.2.	DVSDK .....	14
7.	Resolved Issues .....	14
7.1.	BSP .....	14
8.	Release Content.....	15
8.1.	Software.....	15

8.1.1.	Baseport.....	15
8.1.2.	3D Graphics.....	15
8.1.3.	DVSDK .....	16
8.2.	Documentation .....	16
9.	Support.....	17

## 1. Introduction

This package contains the following items:

- Windows CE 6.0 R3 BSP for the OMAP35x EVM.
- DVSDK Components 1.00.00.04 binaries
- 3D Graphics DDK 1.3 Components binaries
- Prebuilt images
- Documents
- Instructions for building and using the BSP
- New features and features the release supports.

## 2. Release Description

### 2.1. Release Highlights

Below is a list of new updates to the 6.12.04 BSP. For full list of features, see the spreadsheet at <DVSDK\6.12.04\Documentation\Bsquare WinCE BSP for OMAP35x EVM Feature List.pdf>. For release history, see <DVSDK\6.12.04\BSP\readme.txt>.

- **BSP**
  - Updated PowerVR to fix issues found in 6.12.03 release.
  - Minor change to display driver to make debug zones compatible with PowerVR driver.
  - Changed EVM\_3530\_MDC sample OS design to include PowerVR driver by default. Note that if this sample OS design is used, PowerVR from the BSP release must be installed in the PUBLIC tree in order to build successfully.
  - Changed EVM\_3530\_MDC sample OS design to include Silverlight, Flash Lite and XP Skin by default. Note that this sample OS design can only be used with CE6R3.
  - All the sample images included with the BSP have been compiled using CE6R3.
  - Added sample images for EVM2. Note that EMV2 sample images include PowerVR support, Silverlight and the XAMLPERF application.
  - Fixed problem with camera\_mdc driver that caused debug builds to fail if retail build was not done first.
  - Updated EVM\_3530\_MDC sample OS design to add UART1, UART3 and USB OTG
  - BSP feature variables. Note that UART3 (COM3) is still disabled by default in the ti\_evm\_3530.bat file.
  - Updated all software manifest to reflect new release including: WinCE BSP, 3D Graphics and DVSDK Software Manifest
  - Updated WinCE BSP for OMAP3 Product Information

- Updated WinCE BSP Feature List
- **DVSDK**
  - No new updates at this time
- **3D Graphics**
  - Update 3D Graphics DDK to v1.3.1
    - DirectDraw used for 3D graphics presentation to the screen.
    - Improved integration with WinCE6 window compositor
    - VRFB rotation modes supported on ES3 silicon

## 2.2. Release Notices

### 2.2.1. Nomenclature

- BSP refers to the base WinCE kernel drivers
- DVSDK refers to the TI's Digital Video Software Development Kit
- 3D Graphics SDK refers to the TI 3D Graphics Software Development Kit
- EVM1 refers to the TMDXEM3503 platform
- MDC refers to the TI Multimedia Daughter Card
- EVM2 refers to the TMDSEVM3530 platform

### 2.2.2. Sample Build Scripts

Three new sample build scripts with default build settings for the supported platforms are included in this release:

- evm1\_ti\_evm\_3530.bat for TMDXEVM3503
- evm1\_mdc\_ti\_evm\_3530.bat for TMDXEVM3503 + TI Multimedia Daughter Card
- evm2\_ti\_evm\_3530.bat for TMDSEVM3530

Rename the appropriate script to ti\_evm\_3530.bat for building the configuration chosen.

### 2.2.3. Sample OS Design

A new sample OS Design EVM\_3530\_MDC is added in this release providing the OS configuration baseline that supports the TI Multimedia Daughter Card video capture feature. This is only used if you have the Multimedia Daughter Card.

## 2.2.4. Prebuilt Images

The DVSDK and DEMO packages contain prebuilt images to help you verify your systems before starting developing. Each prebuilt image built for the TMDXEVM3503 and TMDSEVM3530 platform using WinCE 6.0 R3 and contains support for a fully functional system with support for USB ActiveSync, accelerated multimedia and 3D graphics support.

- TMDXEVM3503
  - OneNAND LCD (*for TMDXEVM3503 only with Samsung memory*)
  - Micron LCD
  - SD NAND Boot LCD
  - SD NAND Boot DVI 720p
- TMDXEVM3503+MDC
  - Micron LCD
  - SD NAND Boot LCD
  - SD NAND Boot DVI 720p
- TMDSEVM3530
  - Micron LCD
  - SD NAND Boot LCD
  - SD NAND Boot DVI 720p

## 2.2.5. Sample Drivers

The BSP contains several drivers that are provided only as examples. These drivers have not been tested on the EVM and are not supported:

- TI\_EVM\_3530\SRC\DRIVERS\USBHCD
- TI\_EVM\_3530\SRC\DRIVERS\MUSB\USBOTG\_TPS659XX
- TI\_EVM\_3530\SRC\DRIVERS\CAMERA
- TI\_EVM\_3530\SRC\DRIVERS\HEADSET
- PLATFORM\COMMON\SRC\SOC\OMAP35XX\_TPS659XX\_TI\_V1\omap\TPS659XX\BCI
- PLATFORM\COMMON\SRC\SOC\OMAP35XX\_TPS659XX\_TI\_V1\omap\TPS659XX\MADC
- PLATFORM\COMMON\SRC\SOC\OMAP35XX\_TPS659XX\_TI\_V1\omap35xx\HDQ

## 2.2.6. New Directory Structure

With this 6.12 release of the WinCE BSP for OMAP35x EVM, Microsoft separated the System-on-Chip (SoC) libraries from the BSP. This encourages re-use of SoC libraries across multiple OMAP3 BSPs. It also allows independent updates and versioning of the SoC libraries and BSP. The new layout conforms to the recommended BSP structure introduced with CE 6.0.

MSDN describes the organization of BSP and SoC folders at <http://msdn.microsoft.com/en-us/library/aa908532.aspx>.

*This notice is just an FYI for WinCE BSP customers as this configuration has already been done on the WinCE BSP source tree.*

### 3. Installation

This BSP must be used in conjunction with Windows Embedded CE6.0 R3 (R2 can be used). The following tools must be installed in the following order to use this BSP:

- Microsoft Visual Studio 2005 (VS2005)
- Microsoft Visual Studio 2005 Service Pack 1
- Windows Embedded CE6.0 (Plug in for VS2005)
- Windows Embedded CE6.0 Service Pack 1 (SP1)
- Windows Embedded CE6.0 R3 Update
- Windows Embedded CE6.0 Cumulative Product Update Rollup Package 2007 (QFEs)
- Remaining Windows Embedded CE6.0 monthly updates (QFEs)

Once the tools are installed in the correct sequence the TIEVM3530 BSP must be installed into the \WINCE600\PLATFORM and \WINCE600\PLATFORM\COMMON\SRC\SOC directory trees.

This directory has two .zip archives that contain a Microsoft Windows CE 6.00 BSP for the Texas Instruments EVM3530 development board. The TI\_EVM\_3530\_x.xx.xx.zip archive should be unzipped under \WINCE600\PLATFORM to create the platform dependent BSP build tree called TI\_EVM\_3530.

The OMAP35XX\_TPS659XX\_TI\_V1\_x.xx.xx.zip archive should be unzipped under \WINCE600\PLATFORM\COMMON\SRC\SOC to create the platform independent source code tree called OMAP35XX\_TPS659XX\_TI\_V1.



## 4. Build Instructions

For complete instructions on how to build the WinCE BSP platform, see <DVSDK\6.12.04\Documentation\EVM3530 BSP User Guide.pdf>.

### 4.1. Downloading WinCE Image Using Platform Builder

The bootloader supports image download using Platform Builder controlled via the bootloader serial user interface. The following procedure can be used to download the WinCE image onto the device.

- 1) Configure TI OMAP35x EVM hardware
  - Connect serial cable to UART3
  - Connect Ethernet cable to Ethernet jack

*Note: The EVM must be on the same subnet as host PC running Platform Builder.*
- 2) Open Terminal program on host PC (115200, N, 8, 1)
- 3) Power up device
  - Status messages will be displayed on serial port
  - 4 color boot screen will appear
  - On first boot only the flash will be reformatted. This can be a lengthy operation, be patient.
- 4) Launch Platform Builder and open the OS Design project containing the EVM3530 BSP.
- 5) Configure Platform Builder Target Connectivity Options
  - From Target menu select Connectivity Options
  - Select Ethernet as Download transport
  - Click Settings button to display Ethernet settings
  - Start downloads from bootloader serial menu. This will happen automatically if the Ethernet cable is plugged in and a MAC address is programmed. Otherwise program MAC address using menu option 4,9. Once MAC address is programmed exit from menu which will restart download.
  - Select the name string that will appear in Ethernet Settings dialog. It will be in the format EVM3530-xxxxx.
  - Close Target Connectivity Options dialog box
- 6) Select Attach Device from the Target menu in Platform Builder to initiate the download

The OS image will be downloaded, programmed into flash if applicable, and launched. Note that the image will only be programmed into flash if it was built with the IMGFLASH environment variable set.

## 4.2. Programming Bootloader Into NAND/ONENAND

The bootloader can be programmed into flash using EVMFlash tool. This tool is must be used when there is no functional bootloader already located in ONENAND or NAND flash.

Note that the SW4 settings may need to be changed to select a boot device compatible with the cable used by EVMFlash tool to communicate with the EVM.

Please see the documentation provided with that tool for details on its use.

Note that there are 2 versions of the EVM one using Micron NAND and one using Samsung ONENAND and that there are 2 versions of the EVMFlash tool.

## 4.3. Booting from NAND

Note: When switching between NAND and ONENAND builds, you must do a clean build.

Note: To boot the NK.BIN image from the NAND, two things must happen:

- 1) The image must be built to target FLASH (IMGFLASH enabled). This is controlled by the Project->EVM\_3530 Properties..., Configuration Properties, Build Options "Write run-time image to flash memory (IMGFLASH=1)" check box.
- 2) The image must be downloaded to the system using EBOOT and platform builder. After downloading the image the bootloader will write the nk.bin image into the NAND.

Change SW4 to select NAND as the 1st boot device, use one of the following:

Position	1=OFF	2=ON	3=ON	4=ON	5=ON	6=ON	7=OFF	8=OFF (NAND/SSI/USB)
Position	1=ON	2=ON	3=ON	4=OFF	5=ON	6=ON	7=OFF	8=OFF (NAND/SSI/USB/MMC1)
Position	1=OFF	2=OFF	3=OFF	4=OFF	5=ON	6=ON	7=OFF	8=OFF (NAND/USB/UART/MMC1)
Position	1=OFF	2=ON	3=OFF	4=ON	5=OFF	6=ON	7=OFF	8=OFF (NAND/UART)
Position	1=OFF	2=OFF	3=ON	4=OFF	5=OFF	6=ON	7=OFF	8=OFF (NAND/USB)

When using EVMFlash tool with serial cable interface, select UART as the 1st boot device and NAND as the 2nd boot device, change SW4 to:

Position	1=OFF	2=ON	3=OFF	4=ON	5=OFF	6=OFF	7=OFF	8=OFF
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When using EVMFlash tool with USB cable interface, select USB as the 1st boot device and NAND as the 2nd boot device, change SW4 to:

Position	1=OFF	2=OFF	3=ON	4=OFF	5=OFF	6=OFF	7=OFF	8=OFF
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#### 4.4. Booting from SD Memory Card (SD Boot)

Note: The NK.BIN image must be built to target RAM (IMGFLASH disabled). This is controlled by the Project->EVM\_3530 Properties..., Configuration Properties, Build Options "Write run-time image to flash memory (IMGFLASH=1)" check box.

Note: Some older MMC/SD memory cards are not recognized by the CPU internal boot ROM. If you cannot get SD boot to work, be sure to try with other cards. This is an issue with the CPU internal boot ROM and cannot be fixed in the BSP code.

*Note: When switching between NAND and ONENAND builds, you must do a clean build.*

- 1) Format the SD Card under WinXP.
- 2) Make the SD Card bootable using Roadkil's sector editor or another utility:
  - Open the SD card physical sector 0
  - Write 0x80 at offset 0x1BE into the 1st partition
  - Save sector
  - Exit Sector Editor application
- 3) Copy ONLY the MLO file to the SD card. Note that the MLO file is not created during a debug build.
- 4) Copy both the EBOOTSD.NB0 and the NK.BIN files to the SD card.

*Note: steps 1-4 above can be also be accomplished by using the SD Card Boot utility found in the Tools directory.*

- 5) Configure the EVM SW4 switch to select MMC1 as the 1st boot device, use one of the following:

Position	1=ON	2=OFF	3=OFF	4=ON	5=ON	6=ON	7=OFF	8=OFF
Position	1=ON	2=OFF	3=ON	4=ON	5=OFF	6=ON	7=OFF	8=OFF
Position	1=ON	2=ON	3=ON	4=OFF	5=OFF	6=ON	7=OFF	8=OFF

Alternately, when using EVMFlash tool with serial cable interface, configure the EVM SW4 switch to select UART as the 1st boot device and MMC1 as the 2<sup>nd</sup> boot device:

Position	1=ON	2=ON	3=ON	4=OFF	5=OFF	6=OFF	7=OFF	8=OFF
----------	------	------	------	-------	-------	-------	-------	-------

Alternately, when using EVMFlash tool with USB cable interface, configure the EVM

SW4 switch to select USB as the 1st boot device and MMC1 as the 2nd boot device:

Position	1=ON	2=OFF	3=OFF	4=ON	5=ON	6=OFF	7=OFF	8=OFF
----------	------	-------	-------	------	------	-------	-------	-------

- 6) Plug the SD Card into the EVM
- 7) Power on the EVM -> it should boot from SD.

The CPU internal ROM will load the SD XLDR (MLO) and the SD XLDR will load SD EBOOT (ebootsd.nb0). After the SD EBOOT bootloader is running, use the menu to select the SD card as the boot device, and then select continue to boot the NK.BIN file. Note that the MMC/SD boot currently takes about 2 seconds per MB of NK.BIN file size.

## 5. Test Results

For the WinCE BSP QA process, Bsquare uses an internal developed test suite called [Device Validation TestSuite](#) as well as CETK. DVT comes from years of experience from Bsquare testing WinCE environments. It is a use case, system and driver-level testing and performance tool that helps identify BSP functionality and performance gaps. DVT is also used to test TI's 3D graphics and DVSDK frameworks.

Bsquare also tests the WinCE BSP using Microsoft's CETK. The Microsoft tests are ran are documented at <http://msdn.microsoft.com/en-us/library/aa934353.aspx>. There are over 130 functional, performance and stress tests that are ran on each release of the BSP.

Testing and BSP Certification for the 6.12.04 release was done on the TMDXOMAP3503 and TMDSEVM3530 from Mistral. The following is the EVM configuration used during Bsquare's QA process.

- TMDXOMAP3503 EVM board revision D
  - Processor module revision B (ES2.1)
  - Power module revision B
  - MDC revision A
- TMDSEVM3530 EVM board revision G
  - Processor module revision C (ES3.1)
  - Power module revision D

A complete set of test results are available once the WinCE BSP has past General Availability. If you need the complete WinCE BSP QA/Testing results before this date, please email [sales@bsquare.com](mailto:sales@bsquare.com).

## 6. Know Issues

All of the issues below are tracked within internal databases. If you have any questions related to any of these issues or others that are not, contact Bsquare support or [sales@bsquare.com](mailto:sales@bsquare.com).

### 6.1. BSP

- **BSQR#1165** | We have found that CETK test start failing when it got to a 783 byte size sent to 3 addresses. It passed through 2 addresses and 64 bytes to 3 addresses. *This is only related to the CETK Two-Card Network Card Miniport Driver Test. Planned to be fixed in future release.*
- **TIBSQR#1136** | S-video quality is poor on the output of OMAP35x EVM1 and EVM2. Further developing is being done to fix these issues. *Planning to be fixed in future release.*
- **TI#2** | EHCI USB suspend/resume is not currently working. This is being integrated with the PM framework. Meanwhile the workaround for suspend and resume issue is to keep the driver to stay always on. *Planning to be fixed in future release.*
- **BSQR#1175** | Power Management modes have not been tested. *Planning to be tested in future release.*
- **BSQR#0013** | The USB OTG port unstable with hot swap and certain USB1.1 and USB2.0 hubs not working. Standardized USB2.0 hubs do work. *This is known issue with the software + hardware configuration. See <DVSDK\Documentation\App Note - USB Connectivity on TI OMAP3 EVM Platform running Windows CE 6.pdf> for further details.*
- **BSQR#0013** | The USB OTG port is sensitive to the type/length of USB cable used. Recommended cable is GoldX USB 5 in 1 (GXQU-06) available from <http://www.amazon.com>. *This is known issue with the software + hardware configuration. See <DVSDK\Documentation\App Note - USB Connectivity on TI OMAP3 EVM Platform running Windows CE 6.pdf> for further details.*
- **BSQR#0013** | If a device is connected to the OTG port during boot it will sometimes fail to enumerate. Remove and re-insert the cable connected to the OTG port to work around this issue. *This is known issue with the software + hardware configuration. See <DVSDK\Documentation\App Note - USB Connectivity on TI OMAP3 EVM Platform running Windows CE 6.pdf> for further details.*

- **BSQR#1191** | Ethernet driver not working under stress. This is only seen during CETK stress tests and not in normal use. *This was investigated to be an issue with the CETK Test. This will be resolved by Microsoft in the next version of WinCE.*
- **TIBSQR#0013** | When using the USB ECHI controller with the EVM1 + Multimedia Daughter Card, plugging a low/full speed device into the USB port on the daughter card will cause the port to become non-functional until a reboot. To work around this issue, use a hub between the USB port and the low/full speed device. *This behavior is by design (OMAP3 hardware), no fix is expected.*

## 6.2. DVSDK

- **TIFAE#7** | VRFB rotation with video not supported in this release. *An official fix is available for customers from TI. This has not been integrated into the WinCE BSP yet. This is planned for a future release. See TI's site at [http://software-dl.ti.com/dsps/dsps\\_public\\_sw/sdo\\_sb/targetcontent/dvSDK/WinCE/latest/index\\_FDS.html](http://software-dl.ti.com/dsps/dsps_public_sw/sdo_sb/targetcontent/dvSDK/WinCE/latest/index_FDS.html) for more details.*

## 7. Resolved Issues

Below are issues that have been communicated during the last release but changed in status in this release.

### 7.1. BSP

- **BSQR#1183** | EHCI port is not working when DVI mode is enabled. *The issue has been resolved and now working in 6.12.04.*
- **TIBSQR#0044** | The EVM Flash utility does not work for the latest TMDSEVM3530 (EVM2). Texas Instruments is addressing this issue with the EVM provider. As a work-around, please use the SD Boot method. See <DVSDK\Documentation\EVM3530 BSP User Guide.pdf> for procedure on SD Boot. *This is now fixed with new version of the EVMFlash Tool.*
- **BSQR#1216** | Video In driver for the Multimedia Daughter Card is not working efficiently on ES2.1 version of the OMAP35x EVM1. This driver works fine with the ES3.1 upgrade from Mistral. *Resolution for this issue is to either move to ES3.1 upgrade or wait for the next EVM from TI.*

- **TI#46** | Poor multimedia performance has been observed on TMDXEVM3503 platforms using OMAP3530 ES2.1 silicon under certain conditions (such as loading from SD cards). This is seen with high bit rate (>4MBits) H.264 video files. *Resolution for this issue is to upgrade to the production version of the EVM from TI.*

## 8. Release Content

### 8.1. Software

The complete listing of device driver software for baseport, 3D graphics DDK and DVSDK can be found in each software manifest location at the folder <DKSDK\06.12.04\Documentation>.

#### 8.1.1. Baseport

The baseport is found <DVSDK\6.12.04\BSP>. The source for all drivers is location in the zip file marked TI\_EVM\_3530\_6.12.04.zip and OMAP35XX\_TPS659XX\_TI\_V1\_6.12.04.

#### 8.1.2. 3D Graphics

The 3D Graphics DDK package can be found at <DVSDK\6.12.04\PowerVR>. The binary package and demos for the 3D Graphics is located in the zip file marked PowerVR-DDK-1.3.1\_SDK-2.3.1\_OMAP3ES3.x.zip if you are using TMDSEVM3530 platform or PowerVR-DDK-1.3.1\_SDK-2.3.1\_OMAP3ES2.x.zip if you are using TMDXEVM3503 platform. If you are unsure, contact Bsquare support.

To enable accelerated Silverlight support using OpenGL ES 2.0 in the 3D Graphics DDK package, see the section 9, “Building an Image with Windows Embedded CE 6.0 R3” in the Windows Embedded CE 6.0 R3 Install Guide which is found in the R3 distribution’s root directory.

For more information about Silverlight, see <http://www.silverlight.net/>. If you would like help in using Silverlight in your application, contact [sales@bsquare.com](mailto:sales@bsquare.com).

### 8.1.3.DVSDK

The DVSDK package can be found at <DVSDK\6.12.04\BSP>. The binary package for the DVSDK is located in the zip file marked TI\_EVM\_3530\_6.12.04.zip. Once unzipped, the binary files can be found in <\TI\_EVM\_3530\FILES\>.

Source access to the DVSDK can be obtained from Texas Instruments. See [http://software-dl.ti.com/dsps/dsps\\_public\\_sw/sdo\\_sb/targetcontent/dvSDK/WinCE/latest/index\\_FDS.html](http://software-dl.ti.com/dsps/dsps_public_sw/sdo_sb/targetcontent/dvSDK/WinCE/latest/index_FDS.html) for more details.

Video demos and examples can be found online at [http://software-dl.ti.com/dsps/dsps\\_public\\_sw/sdo\\_sb/targetcontent/dvSDK/WinCE/latest/index\\_FDS.html](http://software-dl.ti.com/dsps/dsps_public_sw/sdo_sb/targetcontent/dvSDK/WinCE/latest/index_FDS.html).

## 8.2. Documentation

The following documents are contained in the folder DVSDK\6.12.04\Documentation in the root of the release.

Table 1. List of Documentation

Document	Author	Description
App Note - Enable 3D Graphics Framework on TI OMAP3 EVM Platform running Windows CE 6.pdf	Bsquare	Application note to enable and build the 3D graphics framework (aka 3D Graphics DDK) from TI
App Note - Enable Media Codec Framework on TI OMAP3 EVM Platform running Windows CE 6.pdf	Bsquare	Application note that explains how to enable and build the media codec engine framework (aka DVSDK) from TI
App Note - Enabling DVI Output on the TI EVM Platform running Windows CE 6.pdf	Bsquare	Application note that explains how to configure the WinCE image to output to the DVI port on the EVM
App Note – NEON and VFP in WinCE BSP	Texas Instruments	Application note explaining the limitations of the NEON and VFP instructions in the WinCE BSP.
App Note - USB Connectivity on TI OMAP3 EVM Platform running Windows CE 6.pdf	Bsquare	Application note that describes the USB OTG functionality
App Note - App Note - USB Connectivity on TI OMAP3 EVM Platform running Windows CE 6.pdf	Bsquare	Application note that shows the typical use case for USB OTG for the EVM
App Note - Video Capture Function with the TI OMAP3 EVM Platform.pdf	Bsquare	Application note explaining the video capture software in the WinCE BSP.
Bsquare WinCE BSP 3G DevKit Data	Bsquare	Bsquare's 3G Dev Kit data sheet describing



Sheet for OMAP35x EVM.pdf		the 3G wireless solution for the TI OMAP35x EVM. For more information, email <a href="mailto:sales@bsquare.com">sales@bsquare.com</a> .
BSQUARE WinCE BSP for OMAP35x EVM Data Sheet.pdf	Bsquare	Bsquare's WinCE BSP data sheet describing this WinCE product. For more information, email <a href="mailto:sales@bsquare.com">sales@bsquare.com</a> .
Bsquare WinCE BSP for OMAP35x EVM Feature List.pdf	Bsquare	The complete list of features in the WinCE BSP.
Bsquare WinCE BSP for TI OMAP3 Product Information.pdf	Bsquare	Bsquare Product Information guide for the entire WinCE BSP program including roadmap information. For more information, email <a href="mailto:sales@bsquare.com">sales@bsquare.com</a> .
Bsquare WinCE BSP for TI OMAP3 Release Notes.pdf	Bsquare	This document.
BSQUARE WinCE BSP SDIO Hx White Paper for OMAP35x EVM.pdf	Bsquare	Bsquare's white paper on SDIO Hx that improved the SD interface in the WinCE BSP on OMAP35x EVM. For more information, email <a href="mailto:sales@bsquare.com">sales@bsquare.com</a> .
Bsquare Windows Embedded CE Made Easy	Bsquare	A simple resource guide to explain the WinCE licensing process with Microsoft. For more information, email <a href="mailto:sales@bsquare.com">sales@bsquare.com</a> .
EVM3530 BSP User Guide.pdf	Bsquare	The WinCE BSP user's guide to help guide you through building and running WinCE on the OMAP35x EVM
evm3530_usb_limitation.pdf	Texas Instruments	Describes the USB limitations on the Mistral EVM
OMAP3 WinCE 3D Graphics Software Manifest (1.3.13.2068.3)	Texas Instruments	Lists the 3D Graphics DDK driver/software contained in the BSP and the location of the files.
OMAP3 WinCE BSP Software Manifest (6 12 04).pdf	Bsquare	Lists the WinCE driver/software contained in the BSP and the location of the files.
OMAP3 WinCE DVSDK Software Manifest (1.00.00.04).pdf	Texas Instruments	Lists the DVSDK components contained in the BSP and the location of the files.
WinCE BSP Directory Structure Changes.pdf	Microsoft	Microsoft's description of the WinCE Directory Structure. This is just an FYI document for users as this configuration has already been done on the WinCE BSP source tree.

## 9. Support

- a. For technical support, registered users should contact their local Texas Instruments FAE, or go to our website at <http://www.bsquare.com/omap3>. To get immediate access to the support site, send an email to [omap3support@bsquare.com](mailto:omap3support@bsquare.com) with the subject line "OMAP3 KB ACCESS".

- b. For helpful developer hints, try the collaborative Wiki site at <http://wiki.omap.com/index.php?title=WinCE>.
- c. Users new to Windows Embedded CE6 can obtain evaluation versions of the required software from Microsoft at the following URL <http://msdn.microsoft.com/en-us/embedded/aa731407.aspx>.